



FEATURES:

- Supports 100GBASE 100GE
- Lane bit rate 25.78 Gb/s
- Up to 100km transmission on SMF
- LAN WDM EML laser and PIN receiver with SOA
- Support Multi-Pin function with IntL/RxLOSL and LPMode/TxDIS
- High speed I/O electrical interface (CAUI-4)
- I2C interface with integrated Digital Diagnostic monitoring
- QSFP28 MSA package with duplex LC connector
- Single +3.3V power supply
- Maximum power consumption 6.5 W
- Operating case temperature: 0 to +70 °C
- Compliant to IEEE 802.3bm
- Compliant to SFF-8636 and SFF-8679
- Complies with EU Directive 2015/863/EU

APPLICATIONS:

- 100GBASE-ZR4+

Part Number	Data Rate	Laser	Fiber Type	Distance (km)	Optical Interface	Temperature (°C)	DDMI
QSFP28-EZR4-100-100	103.1Gbps	LANWDM	SMF	100	LC	0~70C	Y

1-ABSOLUTE MAXIMUM RATING:

Exceeding the limits below may damage the transceiver permanently.

Parameter	Symbol	Min	Typ	Max	Unit.	Note
Storage Temperature	Ts	-40	-	85	°C	
Operating Relative Humidity	RH	0	-	85	%	
Supply Voltage	VCC	-0.5	-	4	V	

2-RECOMMENDED OPERATING CONDITIONS

Exceeding the limits below may damage the transceiver permanently.

Parameter	Symbol	Min	Typ	Max	Unit.	Note
Operating Case Temperature	Tc	0	-	70	°C	
Supply Voltage	VCC	3.13	3.3	3.47	V	
Supply Current	ICC	-	-	1.87	A	
Maximum Power Dissipation	Pd	-	-	6.5	W	
Aggregate Bit Rate	Brave	-	103.125	-	Gb/s	
Lane Bit Rate	BRLane	-	25.78	-	Gb/s	
Transmission Distance	TD		-	100 km	Over	SMF with FEC

3- OPTICAL CHARACTERISTICS

Transmitter						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Center Wavelength Lane 0	λ_0	1294.53	1295.56	1296.59	nm	
Center Wavelength Lane 1	λ_1	1299.02	1300.05	1301.09	nm	
Center Wavelength Lane 2	λ_2	1303.54	1304.58	1305.63	nm	
Center Wavelength Lane 3	λ_3	1308.09	1309.14	1310.19	nm	
Total Launch Power, 100GE	P _{ALL}	-	-	14	dBm	1
Average Launch Power per Lane, 100GE	P _{TX_LANE}	3	-	8	dBm	1
Difference in launch power between lanes	P _{TX_DELTA_LANE}	-	-	3.6	dB	
Average Output Power (Laser Turn off)	P _{OUT-OFF}	-	-	-30	dBm	
Side Mode Suppression Ratio	SMSR	30	-	-	dB	
Extinction Ratio, 100GE	ER	6	-	-	dB	
Optical Eye Mask	{0.25,0.4, 0.45, 0.25, 0.28, 0.4}					2
Receiver						
Center Wavelength Lane 0	λ_0	1294.53	1295.56	1296.59	nm	
Center Wavelength Lane 1	λ_1	1299.02	1300.05	1301.09	nm	
Center Wavelength Lane 2	λ_2	1303.54	1304.58	1305.63	nm	
Center Wavelength Lane 3	λ_3	1308.09	1309.14	1310.19	nm	
Average Rx Power per Lane, 100GE	P _{RX_LANE}	-29	-	-3	dBm	3
Difference in launch power between lanes	P _{RX_DELTA_LANE}	-	-	4.5	dB	
LOS Assert	LOSA	-40	-	-	dBm	-
LOS De-assert	LOSD	-	-	-29.5	dBm	
LOS Hysteresis	LOSH	0.5	-	6	dB	

Notes:

- 1. The optical power is launched into SMF.
- 2. Measured with a PRBS 231-1 test pattern @25.78125, Hit ratio≤5E-5.
- 3. Measured with a PRBS 231-1 test pattern @25.78125 Gb/s, BER≤5E-5.

4- ELECTRICAL CHARACTERISTICS

High-Speed Signal: Compliant to CAUI-4 (IEEE 802.3bm)

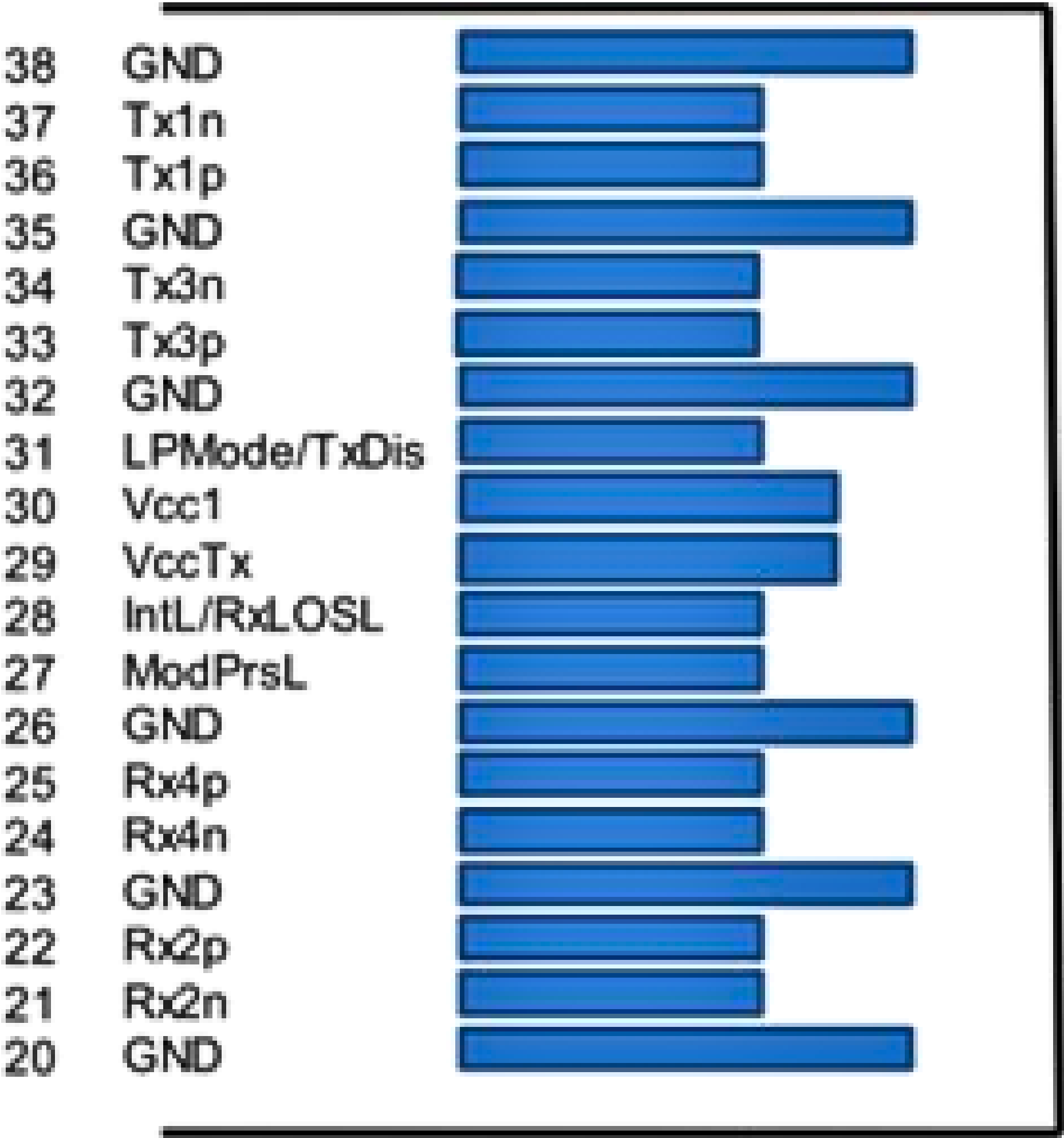
Low-Speed Signal: Compliant to SFF-8679. Table 5-Electrical Characteristics

Transmitter (Module Input)						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Differential Data Input Amplitude	V _{IN,P-P}	85	-	900	mVpp	
Differential Termination Mismatch		-	-	10	%	
Differential input return loss(min)	RLd(f)	Compliance with IEEE802.3ba Equation (83A-5)			dB	
Differential to common mode input return loss (min)	RLdc(f)	Compliance with IEEE802.3ba Equation (83A-6)			dB	
LPMode, Reset and ModSelL, V in low	V _{IL}	-0.3	-	0.8	V	
LPMode, Reset and ModSelL, V in high	V _{IH}	2.0	-	V _{CC} +0.3	V	
Receiver (Module Output)						
Differential Data Output Amplitude	V _{OUT,P-P}	200	-	900	mVpp	
Differential Termination Mismatch (1MHZ)		-	-	10	%	
Transition time, 20% to 80%	Tr Tf	12	-	-	ps	
Differential output return loss (min)	RLd(f)	Compliance with IEEE802.3ba Equation (83A-7)			dB	
Common to differential mode conversion return loss (min)	RLdc(f)	Compliance with IEEE802.3ba Equation (83A-8)			dB	
ModPrsL and IntL, V out low	V _{OL}	0	-	0.4	V	
ModPrsL and IntL, V out high	V _{OH}	V _{CC} -0.5	-	V _{CC} +0.3	V	

5- Digital Diagnostics

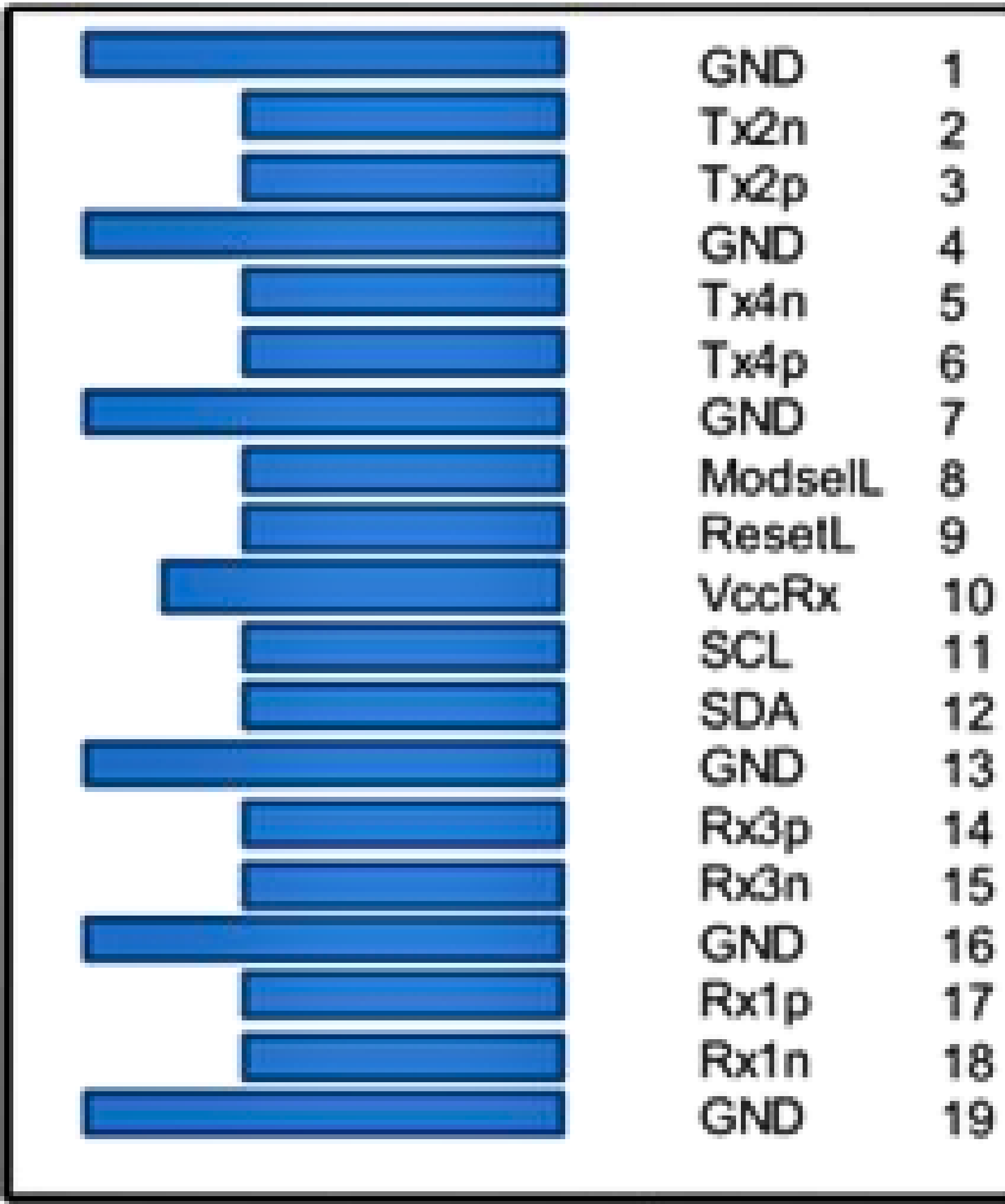
Parameter	Range	Accuracy	Unit	Calibration
Temperature	0 to 70	±3	°C	Internal
Voltage	0 to V _{CC}	±3%	V	Internal
Tx Bias Current Per Lane	0 to 100	±10%	mA	Internal
Tx Output Power Per Lane	3 to 8	±3	dBm	Internal
Rx Power (Each Lane)	-29 to -3	±3	dBm	Internal

6.1-PIN Definitions:



**Top Side
Viewed From Top**

Module Card Edge



**Bottom Side
Viewed From Bottom**

6.2-PIN DESCRIPTIONS

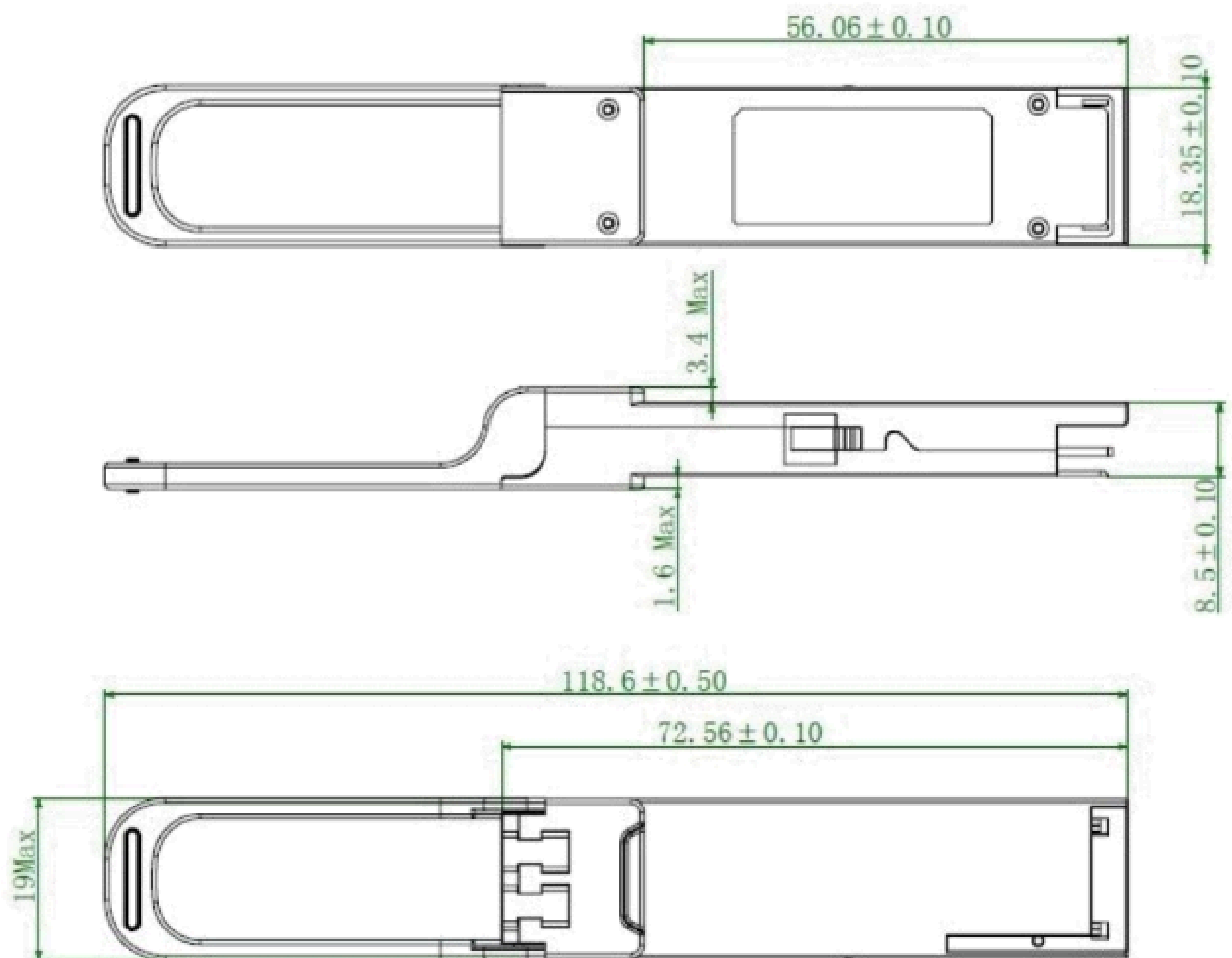
PIN	Logic	Symbol	Description	Plug Seq.	Notes
1		GND	Ground	1	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data output	3	
4		GND	Ground	1	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data output	3	
7		GND	Ground	1	1
8	LVTLL-I	ModSelL	Module Select	3	
9	LVTLL-I	ResetL	Module Reset	3	
10		VccRx	+ 3.3V Power Supply Receiver	2	2
11	LVC MOS-I/O	SCL	2-Wire Serial Interface Clock	3	
12	LVC MOS-I/O	SDA	2-Wire Serial Interface Data	3	
13		GND	Ground	1	
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	
16		GND	Ground	1	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	1
20		GND	Ground	1	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3	
23		GND	Ground	1	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3	
26		GND	Ground	1	1
27	LVTTL-O	ModPrsL	Module Present	3	
28	LVTTL-O	IntL/Rx_LOS	Interrupt/Rx_LOS	3	
29		VccTx	+3.3 V Power Supply transmitter	2	2
30		Vcc1	+3.3 V Power Supply	2	2
31	LVTTL-I	LPMode/TxDIS	Low Power Mode/Tx_Disable	3	
32		GND	Ground	1	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Output	3	
35		GND	Ground	1	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Output	3	
38		GND	Ground	1	1

Note 1:

- GND is the symbol for signal and supply (power) common for the QSFP28 module. All are common within the QSFP28 module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note 2:

- Vcc Rx, VccI and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in MSA. The connector pins are each rated for a maximum current of 1000 mA.

7-Mechanical Dimension

8- Warnings

Handling Precautions: This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.

Laser Safety: Transcom transceiver uses a semiconductor laser system and is a laser class1 product acc. FDA, complies with 21CFR1040.10 and 1040.11. Also this product is a laser class1 product acc. IEC60825-1.